



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC026N04LS		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001706356						
<b>Package</b>		PG-TDSON-8-45		<b>Weight*</b>		118.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.552	0.47	0.47	4674	4674
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
wire	non noble metal	copper	7440-50-8	37.762	31.97	32.01	319628	320044
	noble metal	gold	7440-57-5	0.045	0.04	0.04	383	383
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		739	
	plastics	epoxy resin	-	6.893	5.83		58345	
leadfinish	inorganic material	silicondioxide	60676-86-0	36.646	31.02	36.92	310188	369272
	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12287	12287
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1401	1401
solder	non noble metal	tin	7440-31-5	0.017	0.01		141	
	noble metal	silver	7440-22-4	0.021	0.02		177	
heatspreader	non noble metal	lead	7439-92-1	0.797	0.67	0.70	6749	7067
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.58	9.59	95817	95942
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
*deviation	non noble metal	copper	7440-50-8	22.292	18.87	18.90	188684	188930
						Sum in total:	100.00	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com